



PS7804-1A

4-PIN ULTRA SMALL FLAT-LEAD, LOW ON-STATE RESISTANCE 1-ch Optical Coupled MOS FET

-NEPOC Series-

DESCRIPTION

The PS7804-1A is a low output capacitance solid state relay containing a GaAs LED on the light emitting side (input side) and MOS FETs on the output side.

An ultra small flat-lead package has been provided which realizes a reduction in mounting area of about 50% compared with the PS72xx series.

It is suitable for high-frequency signal control, due to its low $C \times R$, low output capacitance, and low off-state leakage current.

FEATURES

- Ultra small flat-lead package (4.2 (L) × 2.5 (W) × 1.85 (H) mm)
- Low C × R (C × R = 30 pF Ω)
- Low on-state resistance ($R_{on} = 1.1 \Omega TYP$.)
- Large continuous load current (IL = 400 mA)
- 1 channel type (1 a output)
- · Designed for AC/DC switching line changer
- · Low offset voltage
- Ordering number of taping product: PS7804-1A-F3: 3 500 pcs/reel
- · Pb-Free product
- · Safety standards
 - UL approved: No. E72422

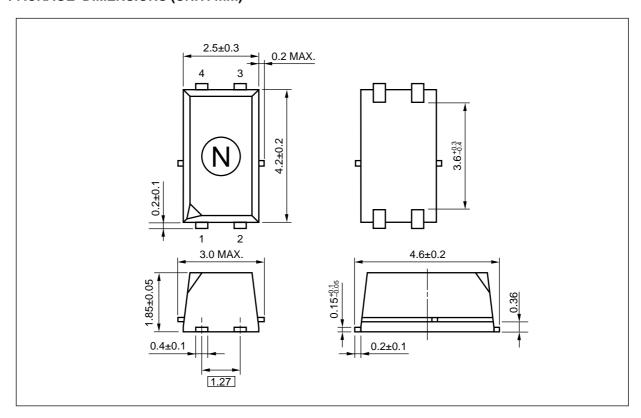
PIN CONNECTION (Top View) 1. LED Anode 2. LED Cathode 3. MOS FET 4. MOS FET

APPLICATIONS

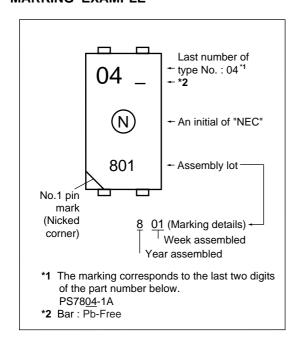
· Measurement equipment

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PACKAGE DIMENSIONS (UNIT: mm)



<R> MARKING EXAMPLE



ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number*
PS7804-1A	PS7804-1A-A	Pb-Free	50 pcs (Tape 50 pcs cut)	Standard products	PS7804-1A
PS7804-1A-F3	PS7804-1A-F3-A		Embossed Tape 3 500 pcs/reel	(UL approved)	

^{*1} For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit	
Diode	Forward Current (DC)	lF	50	mA	
	Reverse Voltage	VR	5.0	V	
	Power Dissipation	PD	50	mW	
	Peak Forward Current *1	IFP	1	Α	
MOS FET	OS FET Break Down Voltage		60	V	
	Continuous Load Current	lι	400	mA	
	Pulse Load Current *2 (AC/DC Connection)	ILP	800	mA	
	Power Dissipation	Po	250	mW	
Isolation Voltage*3		BV	500	Vr.m.s.	
Total Power Dissipation		Рт	300	mW	
Operating Ambient Temperature		TA	-40 to +85	°C	
Storage Temperature		T _{stg}	-40 to +100	°C	

^{*1} PW = 100 μ s, Duty Cycle = 1%

RECOMMENDED OPERATING CONDITIONS (TA = 25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit	
LED Operating Current	lF	4.5	5	20	mA	
LED Off Current	lF	0.1			mA	

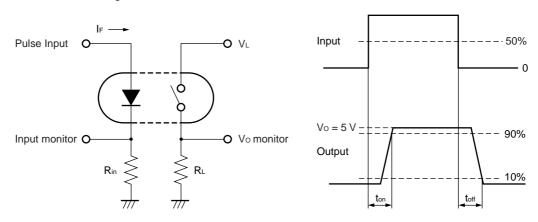
^{*2} PW = 100 ms, 1 shot

^{*3} AC voltage for 1 minute at $T_A = 25$ °C, RH = 60% between input and output. Pins 1-2 shorted together, 3-4 shorted together.

ELECTRICAL CHARACTERISTICS (TA = 25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	I _F = 5 mA		1.1	1.4	V
	Reverse Current	lR	V _R = 5 V			5.0	μА
MOS FET	Off-state Leakage Current	Loff	VD = 60 V		0.1	1.0	nA
	Output Capacitance	Cout	V _D = 0 V, f = 1 MHz		27	35	pF
Coupled	LED On-state Current	IFon	IL = 400 mA			4.0	mA
	On-state Resistance	Ron	$I_F = 5 \text{ mA}, I_L = 400 \text{ mA}, t \le 10 \text{ ms}$		1.1	1.5	Ω
	Turn-on Time*1, 2	ton	IF = 5 mA, Vo = 5 V, RL = 500 Ω ,		0.15	0.5	ms
	Turn-off Time*1, 2	t off	PW ≥ 2 ms		0.05	0. 5	
	Isolation Resistance	R _{I-O}	Vi-o = 0.5 kVpc	10 ⁹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz		0.3		pF

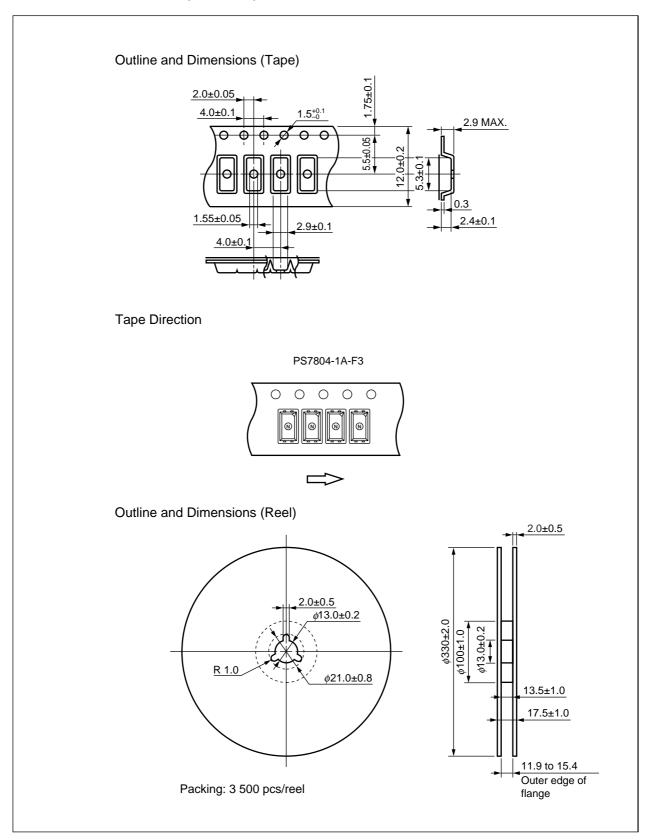
*1 Test Circuit for Switching Time



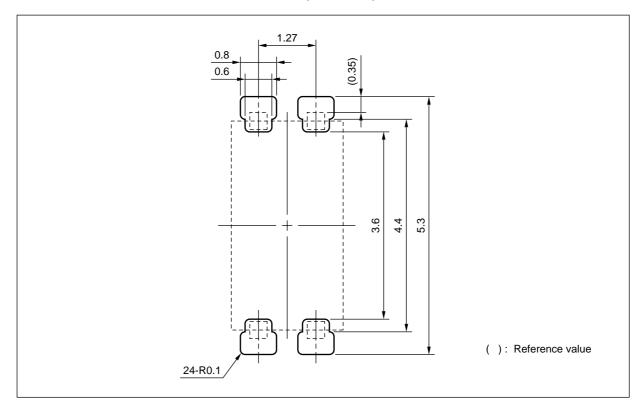
*2 The turn-on time and turn-off time are specified as input-pulse width ≥ 2 ms.

Be aware that when the device operates with an input-pulse width less than 2 ms, the turn-on time and turn-off time will increase.

TAPING SPECIFICATIONS (UNIT: mm)



RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



Remark All dimensions in this figure must be evaluated before use.

RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

Peak reflow temperature
 260°C or below (package surface temperature)

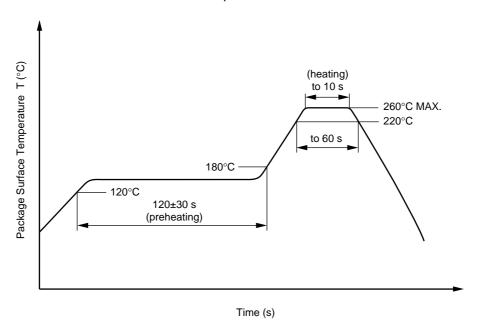
Time of peak reflow temperature
 Time of temperature higher than 220°C
 10 seconds or less
 60 seconds or less

Time to preheat temperature from 120 to 180°C 120±30 s
 Number of reflows Three

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

• Temperature 260°C or below (molten solder temperature)

• Time 10 seconds or less

• Preheating conditions 120°C or below (package surface temperature)

• Number of times One

Flux
 Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

(3) Soldering by soldering iron

Peak temperature (lead part temperature) 350°C or below
 Time (each pins) 3 seconds or less

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

- (a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.
- (b) Please be sure that the temperature of the package would not be heated over 100° C.

(4) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

USAGE CAUTIONS

- 1. Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.

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M8E 02.11-1

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
 - Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.